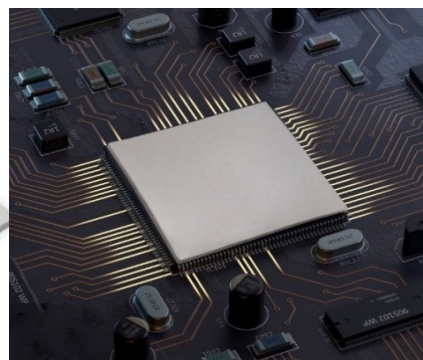
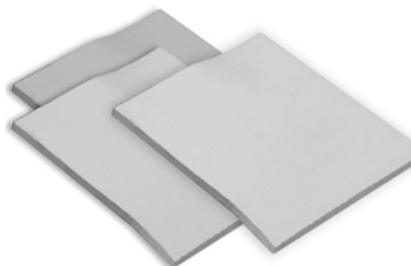




Thermal Pad 21-870

FEATURES & BENEFITS

- Thermal Conductivity :7.0W/m·K
- Extremely Good Thermal Performance
- Excellent Surface Wetting
- High Breakdown Voltage
- Easy For Installation



APPLICATIONS

- Memory Modules
- Mass Storage Devices
- Automotive Electronics
- Telecommunication Hardware
- Radios

JONES Thermal Pad 21-870 is an ultra soft putty like gap filling material rated at a thermal conductivity of 7.0 W/m·K. It is conformable to uneven and rough surfaces, where require excellent compressibility to the thermal gap filler. Its soft construction offers high conformability and imparts minimum pressure to electronic components.

TYPICAL PROPERTIES

Properties		Thermal Pad 21-870	Test Method
Thermal	Thermal Conductivity (W/m·K)	7.0	ASTM D5470
	Operating Temperature Range(°C)	-55~150	JONES Test Method
Physical	Color	Gray	Visual
	Composition	Ceramic&Silicone	-
	Density (g/cm ³)	2.5	ASTM D792
	Thickness Range (mm)	1.0~5.0	ASTM D374
	Thickness Tolerance(mm)> 1mm	±10%	-
	Hardness (Shore 00)	20	ASTM D2240
Electrical	Breakdown Voltage (KV AC/mm)	>1.5	ASTM D149
	Volume Resistivity (Ohm·cm)	10 ¹¹	ASTM D257
	Dielectric Constant@1MHz	6.9	ASTM D150
Regulatory	Flame Rating	V0	UL 94

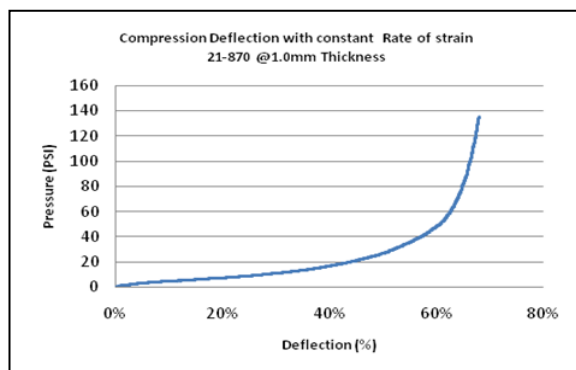


TEST RESULTS

21-870 Gap Pad 1.2 mm Thick; 1 inch² test sample;

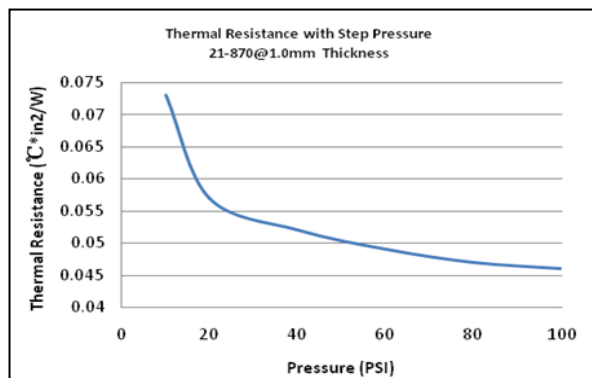
Compression Deflection

Rate of strain = 1.0 mm/min



Thermal Resistance

Pressure step = 10 psi



PART NUMBER SYSTEM

21 - XX AB - YYY

① ② ③ ④ ⑤

① 21-Thermal management material

② XX-Hardness

③ AB-Thermal Conductivity

④ YYY-Optional style

⑤ YYY-Dimension



ORDERING INFORMATION

Recommended Compression

Suitable for wide range of compression.

Standard Size

4" X 8" (100mm X 200mm)

Customizable packaging

Storage Requirement

20°C to 25°C, 50%RH

12 months from date of manufacture.

* Unopened Original Package

HANDLING PRECAUTIONS

FOR SAFE HANDLING

INFORMATION OF THIS PRODUCT,
PLEASE CONTACT WITH YOUR
JONES REPRESENTATIVE FOR THE
SAFETY DATA SHEET (SDS).

LIMITED WARRANTY INFORMATION

The information provided in this Technical Data Sheet including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Jones Corp is not, therefore, liable for the suitability of any Jones Corp products for any specific or general uses. Jones Corp shall not be liable for incidental or consequential damages of any kind.

FOR MORE INFORMATION

About our high performance materials, solutions and capabilities, please visit our website:

<http://www.jones-corp.com>

Disclaimer

- The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the issuing date of this TDS. When using our products, no matter what type of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this TDS are subject to change without prior notice.
- Do not use the products beyond the specifications described in this TDS. This TDS explains the typical performance of the products as individual component. Before use, check and evaluate their operations when installed in your products.
- The product provided in this TDS compliance with HSF.

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